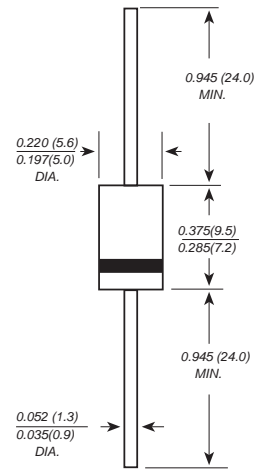


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Open junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
260°C/10 seconds at terminals

Mechanical Data

- Case** : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0345 ounce, 0.98 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SF31	SF32	SF33	SF34	SF35	SF36	SF37	SF38	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	350	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	500	600	V
Maximum average forward rectified current at $T_L=100^\circ C$	$I_{(AV)}$	3.0								A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	150.0								A
Maximum instantaneous forward voltage at 3.0A	V_F	1.0			1.3		1.7			V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ C$ $T_A=100^\circ C$	I_R	5.0				200				μA
Maximum reverse recovery time(Note 1)	T_{rr}	35								ns
Typical junction capacitance (Note2)	C_J	70.0								pF
Typical thermal resistance	R_{qJA}	45.0								$^\circ C/W$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150								$^\circ C$

Note: 1.Reverse recovery time test condition: $I_F=0.5A$ $I_R=1.0A$ $I_{rr}=0.25A$
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

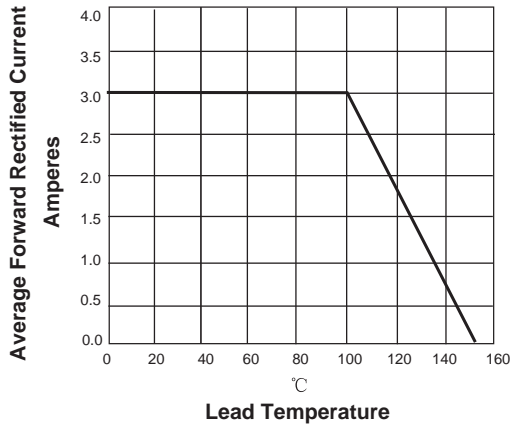


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

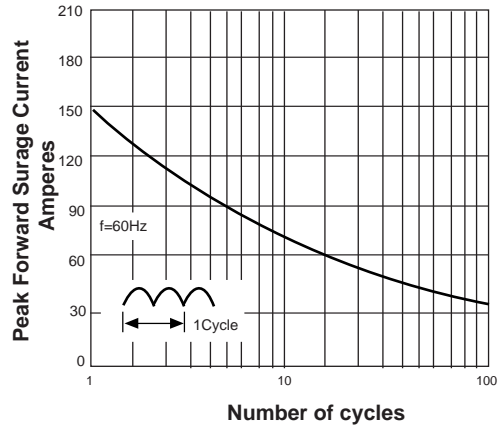


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

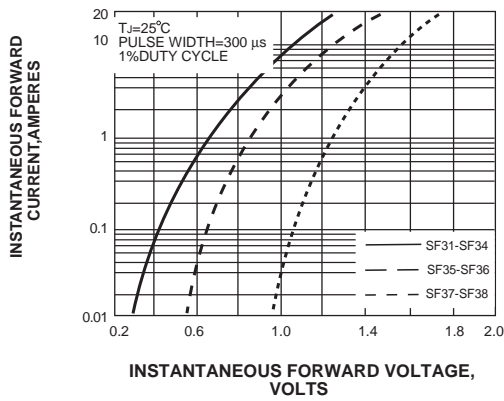
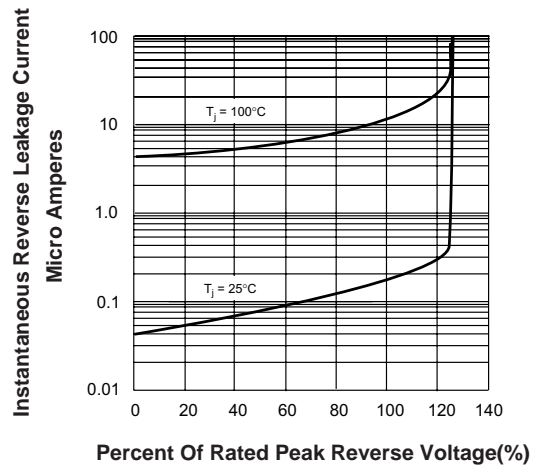
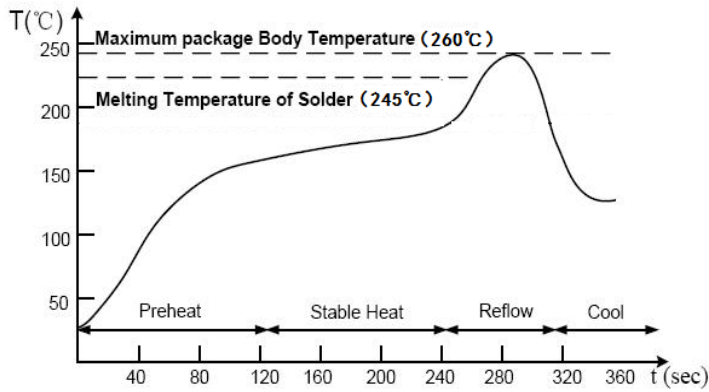


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile

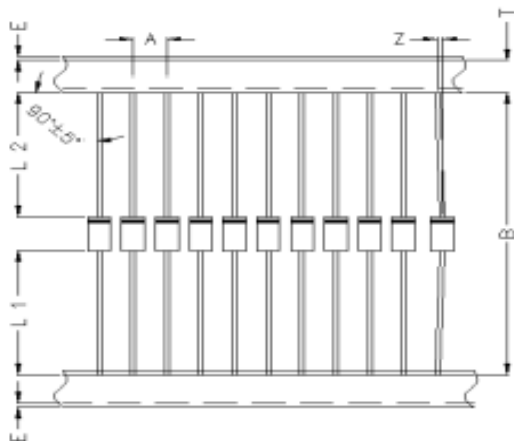


Note

- ◆ Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- ◆ The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- ◆ Devices can be cleaned using standard industry methods and solvents.
- ◆ If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	10.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
DO - 27	255*150*75	1.25	420*276*312	12.5